

L Number	Hits	Search Text	DB	Time stamp
1	726	atomic adj layer adj deposit\$3	USPAT; US-PGPUB	2003/07/09 14:10
2	4830	tantalum adj nitride	USPAT; US-PGPUB	2003/07/09 14:10
3	56129	"TaN"	USPAT; US-PGPUB	2003/07/09 14:10
5	68	(atomic adj layer adj deposit\$3) same ((tantalum adj nitride) or "TaN")	USPAT; US-PGPUB	2003/07/09 14:51

L Number	Hits	Search Text	DB	Time stamp
1	787	438/653.ccls.	USPAT; US-PGPUB	2003/07/09 17:35
2	989168	tungsten or W	USPAT; US-PGPUB	2003/07/09 17:35
3	348610	copper or Cu	USPAT; US-PGPUB	2003/07/09 17:35
4	261	438/653.ccls. and ((tungsten or W) same (copper or Cu))	USPAT; US-PGPUB	2003/07/09 17:37
5	4830	tantalum adj nitride	USPAT; US-PGPUB	2003/07/09 17:38
6	56129	"TaN"	USPAT; US-PGPUB	2003/07/09 17:38
7	185580	barrier	USPAT; US-PGPUB	2003/07/09 17:39
8	3335	((tantalum adj nitride) or "TaN") same barrier	USPAT; US-PGPUB	2003/07/09 17:39
9	116	438/653.ccls. and ((tungsten or W) same (copper or Cu)) and (((tantalum adj nitride) or "TaN") same barrier)	USPAT; US-PGPUB	2003/07/09 17:39